



## ST-200 SERIES SOLUTIONS

*Plasma residue remover*

### Overview

The Entegris series of ST-200 Solutions has been formulated to remove heavily oxidized plasma etch residues from small geometry devices. The products contain no SARA-reportable components such as ethylene glycol ether based solvents, N-Methylpyrrolidone, or highly reactive materials such as hydroxylamine.

### Benefits

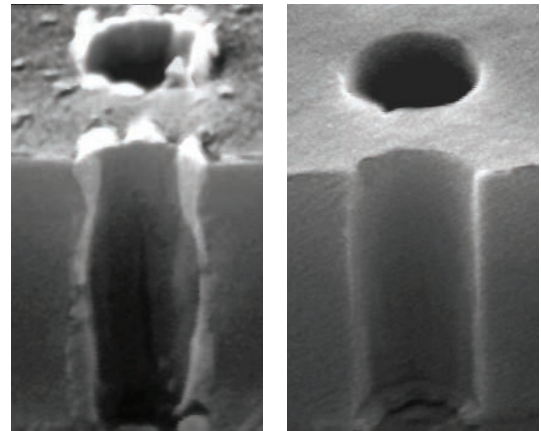
- Strip heavily oxidized plasma deposited residues
- Especially effective for high density residues in sub-0.5 micron vias
- Reduce mobile ion concentrations in oxide surface layers
- Formulated to operate at near-ambient bath temperatures
- Non-corrosive to metals, adhesion layer materials, and low-k dielectrics
- Contain no SARA-reportable materials, hydroxylamines, or catechol
- Require only DI water for post-strip rinse in most applications

### Usage

ST-200 Solutions are formulated as ready-to-use solutions. They are recommended for use on post-ash plasma residues in one-bath hood systems as well as in automatic strip equipment.

### Process

The ST-200 series is intended for removal of post-plasma etch residues from via and metal wafers which have been subjected to full oxygen ashing. For removal of unashed or partially ashed residues, consult Entegris' engineering staff.



*TEOS oxide/TiN/AlCu via (0.35  $\mu\text{m}$ ) after in-situ  $\text{O}_2$  ashing.*

*TEOS oxide/TiN/AlCu via after in-situ  $\text{O}_2$  ashing and processing with Entegris' ST-200 for 45 minutes at 35°C (95°F), DI water rinse, and nitrogen dry.*

### Set-up for Immersion Processing

1. Heat the ST-200 product to 21.5°C–35°C (70.7°F–95°F).
2. Immerse dry wafers into the ST-200 solution for 10–45 minutes.
3. Transfer wafers to an empty DI water dump rinser. Cascade or spray wafers with DI water for 15–20 minutes.
4. Spin dry wafers.

### Corrosion Data

Substrate	Etch Rate Of ST-200 Product at 30°C (86°F)
Al (100%):	2.1 Å/min
AlCu (0.5%):	2.1 Å/min
Copper (100%):	0.2 Å/min
Silicon nitride:	0.3 Å/min
Thermal oxide:	0.03 Å/min
TiN:	0.85 Å/min
Titanium:	0.1 Å/min
Titanium silicide:	<0.1 Å/min
TiW:	0.64 Å/min
W:	0.05 Å/min

## Post-Strip Rinsing

In most applications, wafers may be rinsed directly in DI water after stripping with any of the ST-200 products. If an intermediate solvent rinse is required, Entegris' specially-formulated PSR 200 Post Stripper Rinse is recommended. IPA (isopropyl alcohol), acetone, NMP, butyl carbitol, and butyrolactone are not suitable because of immiscibility and/or particulate formation with ST-200 series products.

## Bath Life

ST-200 solutions will clean a minimum of 1,200 8-inch post ashed wafers utilizing an immersion process. Typical bath life is 24 hours. However, actual bath life and wafer capacity is dependent upon process temperature and configuration.

## Quality Control

ST-200 solutions are manufactured utilizing strict quality controls to maintain Entegris' high standards and to ensure batch-to-batch consistency.

## Storage and Handling

Each ST-200 product has a shelf life of 12 months from date of manufacture if stored in its original, unopened container at 15°C–32°C (60°F–90°F), out of direct sunlight. Refer to Entegris' Material Safety Data Sheet for additional precautions on storage and handling.

## Product Appearance

The color of ST-200 products may vary from nearly water-white to pale yellow to orange-brown. Colors normally vary from batch to batch and may darken over time due to extremely minor amounts of highly colored oxidation by-products. These color differences and/or changes have no effect on functional performance of the products.

## Equipment Compatibility

ST-200 products will attack some plastic materials used in piping and other process equipment. The chart below should serve as a guide for selecting

materials compatible with their use. For information on materials not listed, contact Entegris' technical staff.

### MATERIAL COMPATIBILITY

	@ 25°C (77°F)	@ 35°C (95°F)
BUNA-N rubber:	I	I
EPR o-rings:	M	M
FEP:	C	C
HDPE:	C	C
Hypalon®:	I	I
Kalrez®:	C	C
Neoprene:	I	I
Nylon:	C	C
PFA:	C	C
Polycarbonate:	I	I
Polypropylene:	C	C
Polyurethane:	I	I
PTFE:	C	C
PVC (grey):	M	M
PVC (white):	C	M
PVDF:	C	C
Pyrex®:	I	I
Quartz:	I	I
Stainless steel, 304:	NT	NT
Stainless steel, 316:	C	C
Viton® o-rings:	M	I

C = Compatible I = Incompatible NT = Not Tested  
M = Color change and/or slight weight change (<0.5%)

## Disposal

All waste materials must be disposed of in accordance with local, state, and federal regulations. Refer to Entegris' material safety data sheet for additional data. Do not mix ST-200 series products with acid waste.

## For More Information

Please call your Regional Customer Service Center today to learn what Entegris can do for you. Visit [www.entegris.com](http://www.entegris.com) and select the Customer Service link for the center nearest you.

## Terms and Conditions of Sale

All purchases are subject to Entegris' Terms and Conditions of Sale. To view and print this information, visit [www.entegris.com](http://www.entegris.com) and select the Legal Notices link from the footer.

Entegris®, the Entegris Rings Design® and Creating a Material Advantage® are registered trademarks of Entegris, Inc.; Kalrez®, Hypalon® and Viton® are registered trademarks of E. I. du Pont de Nemours and Company; Pyrex® is a trademark of Corning Incorporated.

### ENTEGRIS, INC.

Corporate Headquarters | 129 Concord Road | Billerica, MA 01821 USA  
Customer Service Tel. +1 952 556 4181 | Customer Service Fax +1 952 556 8022  
In North America 800 394 4083 | [www.entegris.com](http://www.entegris.com)